REQUESTED CHANGE IMPACT ANALYSIS MATRIX

CRANE
AEROSPACE & ELECTRONICS

Change Notification Examples *	Impacts Supplier Design Documentation	Impacts Crane Design Documentation	Other Changes	Describe Impact of Change
Dimensional and Other Parametric Changes				
☐ Changes to part Envelope/Outline dimensions controlled by SCD	☐	☐	☐	
☐ Changes to internal dimensions not controlled by SCD (Must not affect Form, Fit, or Function)	☐	☐	☐	
☐ Correction of fastener interference or fastener installation issues	☐	☐	☐	
☐ Changes to electrical parameters or properties	☐	☐	☐	
☐ Changes to other specified parameters	☐	☐	☐	
Material or Process Changes				
☐ Changes to basic materials of housings, castings, etc.	☐	☐	☐	
☐ Changes to encapsulants, adhesives, sealants, paints, or coatings	☐	☐	☐	
☐ Changes to heat treatments, annealing, surfacing, or finishing	☐	☐	☐	
☐ Changes to plating materials or processes (i.e. electroplating vs. Electrolysis)	☐	☐	☐	
☐ Changes to supplier of key components potentially affecting form, fit, or function	☐	☐	☐	
☐ Changing the supplier of key processes potentially affecting form, fit, or function	☐	☐	☐	

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Change Notification Examples *	Impacts Supplier Design Documentation	Impacts Crane Design Documentation	Other Changes	Describe Impact of Change
Manufacturing Changes				
☐ Changes that employ manufacturing or fabrication techniques that are new or different from what was used for the baseline product design (whether or not controlled by the drawing)	☐	☐	☐	
☐ Use of new or modified tooling, molds, patterns, etc. (includes replacement or reworked tooling)	☐	☐	☐	
☐ Production following upgrade or rearrangement of existing tooling or equipment	☐	☐	☐	
☐ Use of tooling that has been inactive for production for 12 months or more	☐	☐	☐	
☐ Use of tooling transferred to a different plant site or from another plant	☐	☐	☐	
☐ Change of sub-tier supplier for key processes or services.	☐	☐	☐	
☐ Relocation or change of manufacturing facility	☐	☐	☐	
Other Changes				
☐ Changes to test or inspection equipment	☐	☐	☐	
☐ Replacement or Reprogramming of Automated Test Equipment (ATE) for electronic parts	☐	☐	☐	
☐ Use of component parts other than as defined in the SCD	☐	☐	☐	
☐ Changes to supplier's ATP or FTP	☐	☐	☐	